IPC ASSOCIATION CONNE	Material Comp © Copyright 2005. I international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					rials and N	ials and Mfc Information			
upplier Info	ormation														
Company name*			Company unique ID			Ţ	Unique ID Authority					Response Date*			
nsemi											2024-0	2024-05-05			
Contact Name		Title - Contact			I	Phone - Contact*				Email	Email - Contact*				
Product-Env-St	ewards		Product Enviro Compliance			]	NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Repi	resentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
roduct-Env-St	ewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
Requ	ester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	e Versi	on	Manufacturing Site		Weight*	UOM	Unit Type	
		QT3840BC BBIC 4x4 11a		BBIC 4x4 11acn Q	1acn QV840		2024-05-05	4-05-05 TW2		TW2		505.4	mg	Each	
Ianufacturi	ng Proccess Informa	ntion													
Termi	Terminal Plating / Grid Array Material T			Terminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature		ire Max Time at Pea	k Tempera	ature Numb	per of Reflow Cyc	eles		
SnAgCu		CU Alloy 3				<b>260</b> C		C	30	seco	nds 3				
omments															
<b>FTENTION: N</b>	MSL 3 Rated item require	es Bake and D	ry Pack (after	r electrical test)											
or more inform	nation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	16.9	mg	Supplier	Silicon (Si)	7440-21-3		16.9	mg
Die Attach	7.8	mg	Supplier	BISPHENOL A ETHOXYLATE DIMETHACRYLATE	41637-38-1		0.078	mg
			Supplier	oxybis(methyl-2,1-ethanediyl) diacrylate	57472-68-1		0.39	mg
			Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.0195	mg
			Supplier	Silver (Ag)	7440-22-4		7.3125	mg
Laminate Board	163.6	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		49.08	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		49.08	mg
			Supplier	Copper (Cu)	7440-50-8		65.44	mg
Mold Compound-Black	258.1	mg	Supplier	Silica Amorphous (SiO2)	7631-86-9		19.3575	mg
			Supplier	Carbon Black (C)	1333-86-4		1.2905	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		206.48	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		18.067	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		6.4525	mg
			Supplier	Aluminum (Al)	7429-90-5		6.4525	mg
Solder Ball	46.2	mg	Supplier	Silver (Ag)	7440-22-4		1.386	mg
			Supplier	Tin (Sn)	7440-31-5		44.583	mg
			Supplier	Copper (Cu)	7440-50-8		0.231	mg
Solder Mask	10.3	mg	Supplier	Talc	14807-96-6		0.515	mg
			Supplier	Naphthalene	91-20-3		0.206	mg
			Supplier	Phosphinoxide Derivative	Proprietary Data		0.515	mg
			Supplier	2-(2-methoxypropoxy)propanol	34590-94-8		1.236	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		2.369	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		1.442	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		4.017	mg
Substrate Plating	0.7	mg	В	Nickel (Ni)	7440-02-0		0.0888	mg
			Supplier	Gold (Au)	7440-57-5		0.6112	mg
Wire Bond	1.8	mg	Supplier	Palladium (Pd)	7440-05-3		0.0135	mg
			Supplier	Copper (Cu)	7440-50-8		1.7865	mg